

GBU10005 THRU GBU1010

GLASS PASSIVATED BRIDGE RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 10.0 Ampere

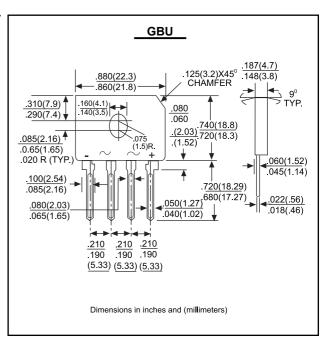
FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capabiliy

MECHANICAL DATA

- Case:Molded plastic, GBU
- Terminals: Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	GBU 10005	GBU 1001	GBU 1002	GBU 1004	GBU 1006	GBU 1008	GBU 1010	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current with Heatsink at $T_{\rm C}$ = 100 °C	I _(AV)	10.0							А
Peak Forward Surge Current, 8.3 ms Single Half-Sine -Wave superimposed on rated load (JEDEC Method)	I _{FSM}	250							A
Maximum Forward Voltage at 5.0 A DC and 25 $^{\rm o}{\rm C}$	V _F	1.0						V	
Maximum Reverse Current at $T_A = 25 \degree C$ at Rated DC Blocking Voltage $T_A = 125 \degree C$	I _R	5.0 500							μA
Typical Junction Capacitance ¹⁾	CJ	70							pF
Typical Thermal Resistance ²⁾	R _{θJC}	2.2							°C/W
Operating and Storage Temperature Range	T _J ,T _S	-55 to +150							°C

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

²⁾ Thermal resistance from junction to case with device mounted on 300 mm X 300 mm X 1.6 mm Cu plate heatsink.



GBU10005 THRU GBU1010 RATINGS AND CHARACTERISTIC CURVES

